



ASSOCIATION CONNECTING
ELECTRONICS INDUSTRIES®

IPC-1710A

OEM Standard for Printed Board Manufacturers' Qualification Profile

Developed by the OEM council of the IPC, the MQP sets the standard for assessing PWB manufacturers capabilities and allows PWB manufacturers to more easily satisfy customer requirements.

IPC-1710A
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A standard developed by IPC

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The material in this standard was developed by the OEM Council of the Institute for Interconnecting and Packaging Electronic Circuits.

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FOREWORD

It is not intended that this Manufacturers' Qualification Profile (MQP) satisfies all the requirements of the customer, however, conscientious maintenance of this document and or registration to ISO 9000 requirements should satisfy the major concerns. Thus, audits should be simpler, required less frequently, and facilitate less paper work as customers and suppliers work closer to meeting each others needs.

ACKNOWLEDGMENTS

The IPC is indebted to the members of the OEM council who participated in the development of this document. A note of thanks is also expressed to the members of the IPC Presidents Council for their review and critique and construction recommendations in finalizing the principles developed for the MQP.

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SECTION 1.1

COMPANY DESCRIPTION

DATE COMPLETED 8/31/2009

GENERAL INFORMATION

LEGAL NAME Triangle Circuits of Pgh, Inc.			
PHYSICAL ADDRESS 931 Third St			
CITY Oakmont	STATE Pa	ZIP 15139	
PROVINCE	COUNTRY USA		
TELEPHONE NUMBER (412)828-5322	FAX NUMBER (412)828-5803	TELEX NUMBER	
E-MAIL ADDRESS Sales@trianglecircuits.com	MODEM NUMBER	DATE FOUNDED X	1979 PRIVATE
INTERNET URL www.trianglecircuits.com	FTP SITE		

MANAGEMENT

CEO Michael D'Ambrosio Sr
General Manager Michael D'Ambrosio Jr
OPERATION MANAGER Don Burgman
QUALITY MANAGER Frank Padol
SALES MANAGER Michael D'Ambrosio Jr
INSIDE SALES MANAGER Jo Anne Faas
WASTE TREATMENT MANAGER (POLLUTION PREVENTION) Jim Clark

CORPORATE DESCRIPTION	NUMBER OF EMPLOYEES		COMMENTS
	CORPORATE	SITE	
DESIGN AND DEVELOPMENT	3	Oakmont	
ENGINEERING	5	Oakmont	
MANUFACTURING CONTROL	2	Oakmont	
MANUFACTURING	DIRECT	35	Oakmont
	INDIRECT		Oakmont
QUALITY CONTROL	QUALITY ENGINEERS	4	Oakmont
	INTERNAL AUDITORS	2	Oakmont
	GENERAL MANAGEMENT	1	Oakmont
ADMINISTRATION	19	Oakmont	
TOTAL	58		

SECTION 1.2

SITE DESCRIPTION

(TO BE COMPLETED FOR EACH SITE)

 DATE COMPLETED 8/31/2009
 ATTACH APPROPRIATE CHARTS (OPTIONAL)

MANUFACTURING FACILITY			
COMPANY NAME	Triangle Circuits of Pgh, Inc		
PHYSICAL ADDRESS	931 Third St		
CITY	Pittsburgh	STATE	Pa
PROVINCE	ZIP 15139		
TELEPHONE NUMBER	(412)828-5322	FAX NUMBER	(412)828-5803
E-MAIL ADDRESS	sales@trianglecircuits.com	MODEM NUMBER	YEARS IN BUSINESS 30
INTERNET URL	www.trianglecircuits.com	FTP	
PRINCIPLE PRODUCTS/SERVICES/SPECIALTIES	BUSINESS CHARACTERIZATION (HIGH VOLUME, QUICK TURN-AROUND, ETC.)		
Printed Circuit Bd Manuf, PCB design, Sales and Marketing, DFM	Quick-turn proto's, low to high volume, off-shore capabilities		

FACILITY MANAGEMENT	TITLE	REPORTS TO (Function/Job Title)
OVERALL OPERATION RESPONSIBILITY FOR THIS SITE Michael D'Ambrosio Jr	General Manager	CEO
MANUFACTURING Don Burgman	Operation Manager	President/COO
TECHNICAL/ENGINEERING John Powell	Engineering	President/COO
MATERIALS/PRODUCTION CONTROL Nick Calabrese	Purchasing Manager	Operation Manager
PURCHASING Same as above		
QUALITY Frank Padol	Quality Manager	President/COO
SALES REPRESENTATIVE Michael D'Ambrosio Jr	Sales Manager	President/COO
WASTE MANAGEMENT Jim Clark	Enviromental Manager	Operation Manager

BUILDINGS	SYSTEMS (INDICATE % COVERAGE)									
	AGE	AREA (Sq. Ft.)	Construction (Wood/Brick)	Power Conditioning	Heating	Ventilation	Air Conditioning	Sprinklers	Waste Treatment	Other
Office	1958	4000	Brick		100	100	100	100	N/A	
Manufacturing	1958	25000	Brick	10	100	100	75	100	100	
Storage	1958	1000	Brick		100	100	100	100	N/A	
Planned additions	1	500	Metal			100				

SAFETY AND REGULATORY AGENCY REQUIREMENTS			
Are fire extinguishers functional and accessible to employees?	X YES	<input type="checkbox"/> NO	What is the distance to the nearest fire station? (in minutes) 5 Minutes
Do you conform to local/federal environment protection agency requirements?	X YES	<input type="checkbox"/> NO	Date of last OSHA visit Date of last EPA visit 12/2/92 7/15/94
Are you currently operating under a waiver or in violation of local government requirements?	<input type="checkbox"/> YES	X NO	Other Agency Audits, UL, ISO 9000, NECQ, CSA Approval and Number X UL # E76719 X ISO 9001-2008 9001-2000 <input type="checkbox"/> CSA # _____ <input type="checkbox"/> Other _____
Do you have a safety program? Describe below.	X YES	<input type="checkbox"/> NO	Hazardous Waste Number Trade Waste Account Number EPA ID #PAD981037377

PLANT PERSONNEL (TOTAL EMPLOYEES)										
Regular	Contract	Office	Technical/Engineering	Production	Full-Time QA	Part-Time QA	Union	Non-Union	Union Name	Contract Expires (Date)
58	0	19	4	35	3	0	0	All		

COMMENTS
Safety program based on internal audits to OSHA standards

SECTION 2.1

PROCESS

DATE COMPLETED 8/31/2009

This section is intended to provide overview information on the processes used to fabricate printed board products.

Site Capability Snapshot (Please Check all that apply)

Designators			Remarks
A	Conductor Forming Processes	XSubtractive <input type="checkbox"/> Thin Foil Subtractive less than .5 oz. <input type="checkbox"/> Semi-Additive <input type="checkbox"/> Additive (Electro-less) <input type="checkbox"/> Black Hole <input type="checkbox"/> Thick Film Paste and Fire <input type="checkbox"/> Thin Film Semi-conductor Sputtering <input type="checkbox"/> Other:	
B	PTH Materials and Processes	XAcid Copper <input type="checkbox"/> Pyro-Phosphate Copper XFull Built Electro-Less <input type="checkbox"/> Gold Paste <input type="checkbox"/> Copper Paste <input type="checkbox"/> Gold Conductor Sputtering <input type="checkbox"/> Nickel Conductor Sputtering <input type="checkbox"/> Other:	
C	Permanent Over-plating	XTin XTin-Lead <input type="checkbox"/> Tin-Nickel Alloy <input type="checkbox"/> Nickel XNickel Gold (Hard) XNickel Gold (Soft) <input type="checkbox"/> Nickel Rhodium <input type="checkbox"/> Conductive Polymer XOther: Carbon Ink, Immersion Silver, Entek, Leadfree HASL	

D	Permanent Selective Plating	<input type="checkbox"/> Tin <input type="checkbox"/> Tin-Lead <input type="checkbox"/> Tin-Nickel Alloy <input type="checkbox"/> Nickel XNickel Gold (Hard) <input type="checkbox"/> Nickel Gold (Soft) <input type="checkbox"/> Nickel Rhodium XOther: Carbon Ink	
E	Permanent Mask or Coating	<input type="checkbox"/> Photo Dry Film XPhoto Liquid <input type="checkbox"/> Image Transfer Screen Mask <input type="checkbox"/> Conformal Coating Solder Mask <input type="checkbox"/> Cover Coat <input type="checkbox"/> Other:	
F	Other Surface Finishes	<input type="checkbox"/> Tin-Lead Fused XImmersion Tin XSolder Leveled <input type="checkbox"/> Roll Soldered <input type="checkbox"/> Electro-less Solder Fused <input type="checkbox"/> Solder Bumped Lands <input type="checkbox"/> Solder Paste Fused XAzole Organic Protective Covering <input type="checkbox"/> Flux Protective Covering XOther: ENIG, Immersion Silver, Leadfree HASL	

SECTION 2.2

ELECTRICAL TEST EQUIPMENT

DATE COMPLETED 8/31/2009

This section is intended to provide overview information on the test equipment and testing capability of the manufacturer.

Site Capability Snapshot (Please Check the column that applies furthest to the right.)

Designators			Remarks
A	Number of Nets	<input type="checkbox"/> <200 <input type="checkbox"/> 200 <input type="checkbox"/> 500 <input type="checkbox"/> 1000 <input type="checkbox"/> 2000 <input type="checkbox"/> 3000 <input type="checkbox"/> 4000 <input type="checkbox"/> 5000 X>5000 <input type="checkbox"/> Other:	
B	Number of Nodes	<input type="checkbox"/> <500 <input type="checkbox"/> 500 <input type="checkbox"/> 1000 <input type="checkbox"/> 2000 <input type="checkbox"/> 3000 <input type="checkbox"/> 4000 <input type="checkbox"/> 5000 <input type="checkbox"/> 6000 X>6000 <input type="checkbox"/> Other:	
C	Probe Point Pitch	<input type="checkbox"/> >1.0 [.040] <input type="checkbox"/> 1.0 [.040] <input type="checkbox"/> 0.8 [.032] <input type="checkbox"/> 0.65 [.025] <input type="checkbox"/> 0.50 [.020] X0.40 [.016] <input type="checkbox"/> 0.30 [.012] <input type="checkbox"/> 0.20 [.008] <input type="checkbox"/> <0.20 [.008] <input type="checkbox"/> Other:	

D	Test % Single Pass	<input type="checkbox"/> None <input type="checkbox"/> <60% <input type="checkbox"/> 60% <input type="checkbox"/> 70% <input type="checkbox"/> 80% <input type="checkbox"/> 90% <input type="checkbox"/> 95% <input type="checkbox"/> 99% <input type="checkbox"/> X100% <input type="checkbox"/> Other:	
E	Probe Accuracy (DTP)	<input type="checkbox"/> >0.2 [.008] <input type="checkbox"/> 0.2 [.008] <input type="checkbox"/> 0.15 [.006] <input type="checkbox"/> 0.125 [.005] <input type="checkbox"/> 0.1 [.004] <input type="checkbox"/> 0.075 [.003] <input type="checkbox"/> X<0.075 [.003] <input type="checkbox"/> Other:	
F	Grid Density	<input type="checkbox"/> Single Side Grid <input checked="" type="checkbox"/> XDouble Sided Grid <input type="checkbox"/> Double Density Grid <input type="checkbox"/> Double Density Double Sided <input type="checkbox"/> Quad Density <input type="checkbox"/> Double Sided Quad Density <input checked="" type="checkbox"/> XFlying Probe <input type="checkbox"/> Other:	
G	Netlist Capability	<input checked="" type="checkbox"/> XGolden Board <input checked="" type="checkbox"/> XIPC-D-356 <input checked="" type="checkbox"/> XNet List Extraction <input checked="" type="checkbox"/> XCAD/CAM Net List Compare <input type="checkbox"/> Other:	

H	Test Voltage	<input type="checkbox"/> <20 VDC <input type="checkbox"/> 20 VDC <input type="checkbox"/> 40 VDC <input type="checkbox"/> 60 VDC <input type="checkbox"/> 80 VDC <input type="checkbox"/> 100 VDC <input type="checkbox"/> X500 VDC <input type="checkbox"/> 1000 VDC <input type="checkbox"/> >1000 VDC <input type="checkbox"/> Other:	
J	Impedance Meas	<input type="checkbox"/> XMicro Section <input type="checkbox"/> Inboard Circuit <input type="checkbox"/> XCoupon <input type="checkbox"/> XManual TDR <input type="checkbox"/> Automated TDR <input type="checkbox"/> Other:	
K	Impedance Tolerance	<input type="checkbox"/> None <input type="checkbox"/> >20% <input type="checkbox"/> 20% <input type="checkbox"/> 15% <input type="checkbox"/> 10% <input type="checkbox"/> 7% <input type="checkbox"/> X5% <input type="checkbox"/> 2% <input type="checkbox"/> <2% <input type="checkbox"/> Other:	

SECTION 2.3

PRODUCT TYPE

DATE COMPLETED
8/31/2009

This section is intended to provide overview information on the printed board product types being fabricated by the manufacturer.

Site Capability Snapshot (Please Check all that apply.)

Designators		Remarks
A	Product Type	<input checked="" type="checkbox"/> Rigid Printed Board <input type="checkbox"/> Flex Printed Board <input type="checkbox"/> Rigid/Flex Board <input type="checkbox"/> Rigid Back Plane <input type="checkbox"/> Molded Product <input type="checkbox"/> Ceramic Printed Board <input type="checkbox"/> Multichip Module <input type="checkbox"/> Laminated Multichip Module <input type="checkbox"/> Deposited Dielectric Multichip Modules <input type="checkbox"/> Other:
B	Circuit Mounting Type	<input checked="" type="checkbox"/> Single Sided <input checked="" type="checkbox"/> Double Sided <input checked="" type="checkbox"/> Multilayer <input type="checkbox"/> Single-sided Bonded to Substrate <input type="checkbox"/> Double-sided Bonded to Substrate <input type="checkbox"/> Multilayer Bonded to Substrate <input type="checkbox"/> Constrained Multilayer <input type="checkbox"/> Distributed Plane Multilayer <input type="checkbox"/> Other:
C	Via Technology	<input type="checkbox"/> No-Vias <input checked="" type="checkbox"/> Thru Hole Vias <input checked="" type="checkbox"/> Buried Vias <input checked="" type="checkbox"/> Blind Vias <input checked="" type="checkbox"/> Thru Hole & Blind Vias <input checked="" type="checkbox"/> Thru Hole & Buried Vias <input checked="" type="checkbox"/> Thru Hole Buried & Blind Vias <input checked="" type="checkbox"/> Buried & Blind Vias <input type="checkbox"/> Other:

D	Laminate Material	<input type="checkbox"/> Phenolic <input type="checkbox"/> Epoxy Paper XEpoxy Glass <input type="checkbox"/> Modified Epoxy Composite <input type="checkbox"/> Polyimide Film & Reinforce <input type="checkbox"/> Cyanate Ester XTeflon <input type="checkbox"/> Ceramic Glass Types <input type="checkbox"/> Various Combinations XOther: Rogers., Taconic	
E	Core Material	<input type="checkbox"/> No Core <input type="checkbox"/> Polymer XCopper <input type="checkbox"/> Aluminum <input type="checkbox"/> Graphite <input type="checkbox"/> Copper Invar/Copper <input type="checkbox"/> Copper Moly/Copper <input type="checkbox"/> Other:	
F	Copper Thickness (Oz.)	<input type="checkbox"/> 1/8 Minimum X1/4 Minimum <input type="checkbox"/> 3/8 Minimum 1/2 Nominal <input type="checkbox"/> 1 Nominal <input type="checkbox"/> 2 Nominal X3-5 Max <input type="checkbox"/> 6-9 Max <input type="checkbox"/> >10 <input type="checkbox"/> Other:	
G	Construction	X≤4 Planes X>4 Planes XTHK to TOL ≤0.2 mm <input type="checkbox"/> THK to TOL >0.2 mm XBow/Twist ≤1% <input type="checkbox"/> Bow/Twist >1% X≤0.3 mm Profile Tolerance <input type="checkbox"/> 0.3 mm Profile Tolerance <input type="checkbox"/> Other:	

H	Coatings and Markings	<p>X ≤ 0.1 mm Mask Clearance</p> <p><input type="checkbox"/> > 0.1 mm Mask Clearance</p> <p>X One Side (Legend)</p> <p>X Two Side (Legend)</p> <p>X None (Legend)</p> <p>X U.L. Material Logo</p> <p>X U.L. V₀ Logo</p> <p><input type="checkbox"/> U.L. V₁ Logo</p> <p><input type="checkbox"/> U.L. V₂ Logo</p> <p><input type="checkbox"/> Other:</p>	
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SECTION 2.4

PRODUCT COMPLEXITY

DATE COMPLETED
8/31/2009

This section is intended to provide overview information on product complexity being fabricated by the manufacturer.

(Please check the column that applies farthest to the right)

Designators			Remarks
A	Board Size Diagonal	<input type="checkbox"/> <250 [10.00] <input type="checkbox"/> 250 [10.00] <input type="checkbox"/> 350 [14.00] <input type="checkbox"/> 450 [17.50] <input type="checkbox"/> 550 [21.50] <input type="checkbox"/> 650 [25.50] <input type="checkbox"/> X750 [29.50] <input type="checkbox"/> 850 [33.50] <input type="checkbox"/> >850 [33.50] <input type="checkbox"/> Other:	
B	Total Board Thickness	<input type="checkbox"/> 1,0 [.040] <input type="checkbox"/> 1,0 [.040] <input type="checkbox"/> 1,6 [.060] <input type="checkbox"/> 2,0 [.080] <input type="checkbox"/> 2,5 [.100] <input type="checkbox"/> X3,5 [.135] <input type="checkbox"/> 5,0 [.200] <input type="checkbox"/> 6,5 [.250] <input type="checkbox"/> >6,5 [.250] <input type="checkbox"/> Other:	
C	Number Conductive Layers	X1-4 X5-6 X7-8 X9-12 <input type="checkbox"/> 13-16 <input type="checkbox"/> 17-20 <input type="checkbox"/> 21-24 <input type="checkbox"/> 25-28 <input type="checkbox"/> >28 <input type="checkbox"/> Other:	

D	Dia Drilled Holes	<input type="checkbox"/> >0,5 [.020] <input type="checkbox"/> 0,5 [.020] <input type="checkbox"/> 0,4 [.016] <input type="checkbox"/> 0,35 [.014] <input type="checkbox"/> 0,30 [.012] <input type="checkbox"/> 0,25 [.010] <input type="checkbox"/> 0,20 [.008] <input type="checkbox"/> X0,15 [.006] <input type="checkbox"/> <0,15 [.006] <input type="checkbox"/> Other:	
E	Total PTH TOL (Max-Min)	<input type="checkbox"/> >0,250 [.010] <input type="checkbox"/> 0,250 [.010] <input type="checkbox"/> 0,200 [.008] <input type="checkbox"/> 0,150 [.006] <input type="checkbox"/> 0,125 [.005] <input type="checkbox"/> 0,100 [.004] <input type="checkbox"/> X0,075 [.003] <input type="checkbox"/> 0,050 [.002] <input type="checkbox"/> <0,050 [.002] <input type="checkbox"/> Other:	
F	Hole Location TOL DTP	<input type="checkbox"/> >0,50 [.020] <input type="checkbox"/> 0,50 [.020] <input type="checkbox"/> 0,40 [.016] <input type="checkbox"/> 0,30 [.012] <input type="checkbox"/> 0,25 [.010] <input type="checkbox"/> 0,20 [.008] <input type="checkbox"/> 0,15 [.006] <input type="checkbox"/> 0,10 [.004] <input type="checkbox"/> X<0,10 [.004] <input type="checkbox"/> Other:	
G	Internal Layer Clearance (Min)	<input type="checkbox"/> >0,350 [.014] <input type="checkbox"/> 0,350 [.014] <input type="checkbox"/> X0,250 [.010] <input type="checkbox"/> 0,200 [.008] <input type="checkbox"/> 0,150 [.005] <input type="checkbox"/> 0,125 [.005] <input type="checkbox"/> 0,100 [.004] <input type="checkbox"/> 0,075 [.003] <input type="checkbox"/> <0,075 [.003] <input type="checkbox"/> Other:	

H	Internal Layer Conductor Width (Min)	<input type="checkbox"/> >0,250 [.010] <input type="checkbox"/> 0,250 [.010] <input type="checkbox"/> 0,200 [.008] <input type="checkbox"/> 0,150 [.006] <input type="checkbox"/> 0,125 [.005] <input type="checkbox"/> X0,100 [.004] <input type="checkbox"/> 0,075 [.003] <input type="checkbox"/> 0,050 [.002] <input type="checkbox"/> <0,050 [.002] <input type="checkbox"/> Other:	
J	Internal Layer Process Allowance	<input type="checkbox"/> >0,100 [.004] <input type="checkbox"/> 0,100 [.004] <input type="checkbox"/> 0,075 [.003] <input type="checkbox"/> 0,050 [.002] <input type="checkbox"/> 0,040 [.0015] <input type="checkbox"/> 0,030 [.0012] <input type="checkbox"/> 0,025 [.001] <input type="checkbox"/> X0,020 [.0008] <input type="checkbox"/> <0,020 [.0008] <input type="checkbox"/> Other:	
K	External Layer Clearance (Min)	<input type="checkbox"/> >0,350 [.014] <input type="checkbox"/> 0,350 [.014] <input type="checkbox"/> 0,250 [.010] <input type="checkbox"/> 0,200 [.008] <input type="checkbox"/> 0,150 [.006] <input type="checkbox"/> 0,125 [.005] <input type="checkbox"/> X0,100 [.004] <input type="checkbox"/> 0,075 [.003] <input type="checkbox"/> <0,075 [.003] <input type="checkbox"/> Other:	

L	External Layer Conductor Width (Min)	<input type="checkbox"/> >0,250 [.010] <input type="checkbox"/> 0,250 [.010] <input type="checkbox"/> 0,200 [.008] <input type="checkbox"/> 0,150 [.006] <input type="checkbox"/> 0,125 [.005] <input type="checkbox"/> X0,100 [.004] <input type="checkbox"/> 0,075 [.003] <input type="checkbox"/> 0,050 [.002] <input type="checkbox"/> <0,050 [.002] <input type="checkbox"/> Other:	
M	External Layer Process Allowance	<input type="checkbox"/> >0,100 [.004] <input type="checkbox"/> 0,100 [.004] <input type="checkbox"/> 0,075 [.003] <input type="checkbox"/> 0,050 [.002] <input type="checkbox"/> 0,040 [.0015] <input type="checkbox"/> 0,030 [.0012] <input type="checkbox"/> 0,025 [.001] <input type="checkbox"/> X0,020 [[.0008] <input type="checkbox"/> <0,020 [.0008] <input type="checkbox"/> Other:	
N	Feature Location DTP	<input type="checkbox"/> >0,50 [.020] <input type="checkbox"/> 0,50 [.020] <input type="checkbox"/> 0,40 [.016] <input type="checkbox"/> 0,30 [.012] <input type="checkbox"/> 0,25 [.010] <input type="checkbox"/> 0,20 [.008] <input type="checkbox"/> 0,15 [.006] <input type="checkbox"/> 0,10 [.004] <input type="checkbox"/> X<0,10 [.004] <input type="checkbox"/> Other:	

All Dimensions are in millimeters [inches shown in brackets]

SECTION 2.5

QUALITY DEVELOPMENT

DATE COMPLETED 8/31/2009

This section is intended to provide overview information on the quality systems in place in the manufacturing facility.

Site Capability Snapshot (Please Check all that apply.)

Designators			Remarks
A	Strategic Plan	XFunctional Steering Committee Formed <input type="checkbox"/> TQM Plan & Philosophy Established & Published XDocumented Quality Progress Review XImplementation & review of Project Team Recommendations XTQM Communicated throughout organization XControlled New process Start-up XManagement Participates in TQM Audits XEmployee Recognition Program <input type="checkbox"/> Total TQM Plan/Involvement Customer Training <input type="checkbox"/> Other:	
B	Employee Involvement	XCertified Training Available XTraining of Employee Base <input type="checkbox"/> TQM Team Trained <input type="checkbox"/> Design of Experiment Training and Use XNew Process Implementation Training XSupport Personnel Training <input type="checkbox"/> Advanced Statistical Training <input type="checkbox"/> Quality Functional Deployment XOngoing Improvement Program for Employees <input type="checkbox"/> Other:	
C	Quality Manual	<input type="checkbox"/> Quality Manual Started <input type="checkbox"/> Generic Quality Manual for Facility <input type="checkbox"/> 10% of manufacturing depts. have process specifications <input type="checkbox"/> 25% of manufacturing depts. have process specifications <input type="checkbox"/> 50% of manufacturing depts. have process specifications XNon-manufacturing Manuals Developed <input type="checkbox"/> 25% of all departments have quality manuals <input type="checkbox"/> 50% of all departments have quality manuals XAll Manufacturing and support depts. have controlled quality manual <input type="checkbox"/> Other:	

D	Instructions	<input type="checkbox"/> Work Instructions Started <input type="checkbox"/> Quality Instructions Started <input type="checkbox"/> 10% Work Instructions Completed <input type="checkbox"/> 10% Quality Instructions Completed <input type="checkbox"/> 25% Work Instructions Completed, Controlled <input type="checkbox"/> 25% Quality Instructions Completed, Controlled <input type="checkbox"/> 50% Work Instructions Completed, Controlled <input type="checkbox"/> 50% Quality Instructions Completed, Controlled <input checked="" type="checkbox"/> Quality and work Instruct. Completed, Controlled <input type="checkbox"/> Other:	
E	SPC Implementation IPC-PC-90	<input checked="" type="checkbox"/> Plan Exists <input checked="" type="checkbox"/> Training Started <input checked="" type="checkbox"/> Process Data Collected & Analyzed <input type="checkbox"/> All Employees Trained <input type="checkbox"/> First Process Stable & Capable <input checked="" type="checkbox"/> Several Major Processes Stable & Capable <input checked="" type="checkbox"/> Continued Improvement of Stable Processes <input type="checkbox"/> Additional Mfg Processes under Control <input type="checkbox"/> All Processes Under Control <input type="checkbox"/> Other:	
F	Supplier Programs/Controls	<input type="checkbox"/> Supplier Rating Program <input type="checkbox"/> Monthly Analysis Program <input type="checkbox"/> Key Problems Identified <input checked="" type="checkbox"/> Supplier Reviews Performance Data provided <input type="checkbox"/> TQM Acceptance by suppliers <input type="checkbox"/> 10% of Suppliers Using SPC <input type="checkbox"/> 25% of Suppliers Using SPC <input type="checkbox"/> 50% of Suppliers Using SPC <input type="checkbox"/> All Key Suppliers using Certified parts program <input type="checkbox"/> Other:	
G	Third Party IPC-QS-95	<input type="checkbox"/> Instrument Controls in Place <input type="checkbox"/> Measurement System in Control IPC-PC-90 <input checked="" type="checkbox"/> Document Controls in Place <input checked="" type="checkbox"/> Reduced Lot Sampling <input type="checkbox"/> 10% of Processes Under Audit Control <input checked="" type="checkbox"/> 50% or Greater of Processes Under Audit Control <input type="checkbox"/> ISO-9003 Certified <input type="checkbox"/> ISO-9002 Certified <input type="checkbox"/> ISO-9001 <input checked="" type="checkbox"/> Other: ISO9001-2000	

SECTION 3**EQUIPMENT PROFILE (Pre-Site Audit)**

DATE COMPLETED

8/31/2009

* Examples of equipment limitations include:
min/max board size & min/max working area

3.1 PHOTOTOOL CAPABILITY	YES	NO	EQUIPMENT	QTY	EQUIPMENT LIMITS
A) AOI of phototool	X	<input type="checkbox"/>	Camtek	1	
B) AOI CAD reference (CAM)	X	<input type="checkbox"/>	Valor Genesis	1	
C) Photoplotting	X	<input type="checkbox"/>	Gerber Cresent	1	
D) Photo reductions	X	<input type="checkbox"/>	Sub-contracted		
E) Film scan and conversion	X	<input type="checkbox"/>	Sub-contracted		
F) Film processing <input type="checkbox"/> air-dried <input type="checkbox"/> force-dried X processed in automatic processor	X	<input type="checkbox"/>	Dupont	1	
G) Media types X silver halide film <input type="checkbox"/> glass X diazo	X	<input type="checkbox"/>	Dupont James River	N/A	

3.2 DRILLING EQUIPMENT	YES	NO	EQUIPMENT	QTY	EQUIPMENT LIMITS
A) Manual	<input type="checkbox"/>	X			
B) Optical (single spindle)	<input type="checkbox"/>	X			
C) N.C. drill	X	<input type="checkbox"/>	Pluritec Excellon Mark 6	2 each	8" 9" min panel 20" * 24" Max

3.3 ROUTING EQUIPMENT	YES	NO	EQUIPMENT	QTY	EQUIPMENT LIMITS
A) Edge beveler	X	<input type="checkbox"/>	Radoll	1	
B) Hand router (pin router)	<input type="checkbox"/>	X			
C) N.C. router	<input type="checkbox"/>	X			
D) N.C. driller/router	X	<input type="checkbox"/>	Excellon	3	
E) Scoring (profile)	X	<input type="checkbox"/>	Excellon	1	
F) Scoring (straight line)	X	<input type="checkbox"/>	Anita	1	

3.4 MECHANICAL EQUIPMENT	YES	NO	EQUIPMENT	QTY	EQUIPMENT LIMITS
A) Punch press	X				Off shore supplier
B) Shear	X	<input type="checkbox"/>	Tenumith	2	
C) Milling machine	X				Sub contract basis

3.5 HOLE PREPARATION (DESMEAR)	YES	NO	EQUIPMENT	QTY	EQUIPMENT LIMITS
A) Permagnate	X	<input type="checkbox"/>	Tank-vertical line	1	
B) Plasma	X				Sub contract basis
C) Mechanical	<input type="checkbox"/>	X			
D) Etchback	X	<input type="checkbox"/>	Tank-vertical line	1	

3.6 PRIMARY IMAGE APPLICATION	YES	NO	EQUIPMENT	QTY	EQUIPMENT LIMITS
A) Dry film	X	<input type="checkbox"/>	Hot roll laminations	2	
B) Hand screening	<input type="checkbox"/>	X			
C) Machine screening	<input type="checkbox"/>	X			
D) Wet film	<input type="checkbox"/>	X			
E) Liquid photoimageable	<input type="checkbox"/>	X			

3.7 TYPE OF TREATMENT FOR MULTILAYER INNERLAYERS	YES	NO	EQUIPMENT	QTY	EQUIPMENT LIMITS
A) Black oxide		X			
B) Red oxide	<input type="checkbox"/>	X			
C) Copper scrub		X			
D) Durabond	<input type="checkbox"/>	X			
E) Other	X		Oxide reduction Chem clean		

3.8 LAMINATION	YES	NO	MATERIAL	QTY	APPLICATION TECHNIQUE
A) High pressure	X	<input type="checkbox"/>	Burkle Walbash	1 1	
B) High temperature	X	<input type="checkbox"/>	Burkle Walbash	1 1	
C) Vacuum	X	<input type="checkbox"/>	Burkle	1	
D) Vacuum assist	<input type="checkbox"/>	<input type="checkbox"/>			
E) Foil heat assist	<input type="checkbox"/>	<input type="checkbox"/>			
F) Separate cool-down	X	<input type="checkbox"/>		2	

3.9 ELECTROLESS COPPER PLATING	YES	NO	EQUIPMENT	QTY	EQUIPMENT LIMITS
A) Fully additive application	<input type="checkbox"/>	<input type="checkbox"/>			
B) Electroless deposition (semiadditive)	<input type="checkbox"/>	<input type="checkbox"/>			
C) Through-hole and via	X	<input type="checkbox"/>	In line process	1	

3.10 COPPER ELECTROPLATING	YES	NO	EQUIPMENT	QTY	EQUIPMENT LIMITS
A) Copper sulfate	X	<input type="checkbox"/>	In line process	1	
B) Pyrophosphate	<input type="checkbox"/>	<input type="checkbox"/>			
C) Copper fluoborate	<input type="checkbox"/>	<input type="checkbox"/>			
D) Other	<input type="checkbox"/>	<input type="checkbox"/>			

3.11 TIN/LEAD SURFACE PLATINGS/COATINGS	YES	NO	EQUIPMENT	QTY	EQUIPMENT LIMITS
A) Tin/lead electroplated	<input type="checkbox"/>	X			
B) Immersion tin or tin/lead (electroless)	X	<input type="checkbox"/>			
C) Hot air solder leveled (HASL)	X	<input type="checkbox"/>			

3.12 FUSING PROCESSES	YES	NO	EQUIPMENT	QTY	EQUIPMENT LIMITS
A) I.R. reflow	<input type="checkbox"/>	<input type="checkbox"/>			
B) Hot oil reflow	<input type="checkbox"/>	<input type="checkbox"/>			
C) Horizontal (hot air level)	X	<input type="checkbox"/>			Sub contract basis
D) Vertical (hot air level)	X	<input type="checkbox"/>			

3.13 NICKEL SURFACE PLATING	YES	NO	EQUIPMENT	QTY	EQUIPMENT LIMITS
A) Electroless nickel	X	<input type="checkbox"/>			
B) Electroplated nickel	X	<input type="checkbox"/>			

3.14 GOLD SURFACE PLATING	YES	NO	EQUIPMENT	QTY	EQUIPMENT LIMITS
A) Electroless gold	X	<input type="checkbox"/>			
B) Electroplated gold	X	<input type="checkbox"/>			

3.15 PALLADIUM SURFACE PLATING	YES	NO	EQUIPMENT	QTY	EQUIPMENT LIMITS
A) Electroless palladium (immersion)	X	<input type="checkbox"/>			Off shore supplier
B) Electroplated palladium	X	<input type="checkbox"/>			Off shore supplier

3.16 SOLDERMASK	YES	NO	EQUIPMENT	QTY	EQUIPMENT LIMITS
A) Screened deposited image	<input type="checkbox"/>	<input type="checkbox"/>			
B) Dry film photoimageable	<input type="checkbox"/>	<input type="checkbox"/>			
C) Liquid photoimageable	X	<input type="checkbox"/>			
D) Dry film/liquid combination	<input type="checkbox"/>	<input type="checkbox"/>			

3.17 ORGANIC SURFACE PROTECTION	YES	NO	EQUIPMENT	QTY	EQUIPMENT LIMITS
A) Benzotriazole	<input type="checkbox"/>	<input type="checkbox"/>			
B) Imidazole	<input type="checkbox"/>	<input type="checkbox"/>			
C) Benzimidazole	X	<input type="checkbox"/>			

3.18 MICROSECTION CAPABILITY	YES	NO	EQUIPMENT	QTY	EQUIPMENT LIMITS
A) Manual	X	<input type="checkbox"/>			
B) Single cavity automated	<input type="checkbox"/>	<input type="checkbox"/>			
C) Multiple cavity automated	<input type="checkbox"/>	<input type="checkbox"/>			
D) Plating thickness analysis	X	<input type="checkbox"/>			

3.19 CHEMICAL ANALYSIS	YES	NO	EQUIPMENT	QTY	EQUIPMENT LIMITS
A) Etching chemistry	X	<input type="checkbox"/>			
B) Plating chemistry	X	<input type="checkbox"/>			
C) Effluent (PPM) analysis	X	<input type="checkbox"/>			

3.20 ELECTRICAL TEST EQUIPMENT	YES	NO	EQUIPMENT	QTY	EQUIPMENT LIMITS
A) Continuity and shorts	X	<input type="checkbox"/>			
B) Fixture development	X	<input type="checkbox"/>			
C) Flying probe test	X	<input type="checkbox"/>			
D) Impedance control	X	<input type="checkbox"/>			

SECTION 4

TECHNOLOGY PROFILE SPECIFICS

DATE COMPLETED 8/31/2009

4.1 ADMINISTRATION

4.1.1 CAPACITY PROFILE	EST %	COMMENTS
A) Total annual capacity in square meters (surface area) per month	293KSQ'	Based on 375 18 * 24 panel per day
B) Presently running at ____ % of capacity	60	

4.1.2 PERCENTAGE OF DOLLAR VOLUME	EST %	COMMENTS
A) Single sided (rigid)	2	
B) Double sided (rigid)	40	
C) Multilayer (rigid)	58	
D) Single side (unreinforced-flex)	N/A	
E) Double sided (unreinforced-flex)	N/A	
F) Multilayer (unreinforced-flex)	N/A	
G) Multilayer (rigid/flex)	N/A	

4.1.3 PANEL PRODUCTION PROFILE	UNITS PER MONTH
A) Size of a production lot in panels	
1) Normal	17-20 panels
2) Smallest	1-2 panels
B) Number of panels per month	
1) High Production	
2) Medium Production	
3) Low Production	
3) Short run	
4) Prototype	

C) Average lead time (delivery) as defined in B)			
1) High Production		4-6wks	
2) Medium Production		2-3wks	
3) Low Production		2wks	
3) Short run		1-2wks	
4) Prototype		3-5 days	
Quick turn - No. of days <u>3 & 5.</u>			
D) Product delivered in full panel or array sub-panel format			
1) Total in panel or array format		35% array or pallet	
2) Scored format		50%	
3) Tab breakaway format		50%	
4) Other		N/A	
5) Total to customer layout		75%	
6) Total to manufacturing layout		25%	
E) Product delivered in board format			
1) Total in board format		65%	
2) Extracted: scored to size		0	
3) Extracted: sheared to size		0	
4) Extracted: routed to size		100%	
4.1.4 APPROVAL AND CERTIFICATION	YES	NO	COMMENTS
A) Company approvals			
1) UL approval	X	<input type="checkbox"/>	94V Level <u>0</u>
2) Canadian standards	<input type="checkbox"/>	X	
3) MIL-P-55110	X		Compliant
4) MIL-P-50884	<input type="checkbox"/>	X	
5) ISO-9002	<input type="checkbox"/>	X	
6) ISO-9001	X	<input type="checkbox"/>	ISO9001-2008

7) ISO-14000	<input type="checkbox"/>	X	
8) BABT	<input type="checkbox"/>	X	
9) EEC	<input type="checkbox"/>	X	
10) Customer satisfaction	X	<input type="checkbox"/>	Customer satisfaction survey 2X/yr
B) Other certification information			
1)Laminate	X	<input type="checkbox"/>	C of C supplied
2)Quality standards	X		IPC Class 3
3)Equipment calibration	X	<input type="checkbox"/>	NIST Traceable

4.1.5 CUSTOMER INTERFACE PROFILE	YES	NO	COMMENTS
A) Modem capability		X	
B) Baud rate			N/A all e-mail
C) Data verification technique	X	<input type="checkbox"/>	Auto verification in CAM system
D) Engineering change order process	X	<input type="checkbox"/>	
E) Job status reporting to customers	X	<input type="checkbox"/>	Inside sales phone e-mail contact

4.1.6 OTHER CAPABILITIES	YES	NO	COMMENTS
A) Facility research and development	X	<input type="checkbox"/>	As performed by engineer and techs
B) (Automated) On-line shop floor control/MRP system	X	<input type="checkbox"/>	Automated WIP tracking and Quality system
C) Process control system	X	<input type="checkbox"/>	
D) Operator training system	X	<input type="checkbox"/>	

4.2 PROCESS ORIENTATION

4.2.1 LAMINATE MATERIAL	EST %	COMMENTS
A) Most commonly used laminates (G10, FR4, etc.)	15 85 15 85	Brand name ISOLA Type FR-4 MLB Brand name Shengyi Type FR-4 MLB Brand name King Bd Type FR-4 2/S Brand name Shengyi Type FR-4 2/S
B) Other laminate material		
1) Planar resistor layers		UL approved <input type="checkbox"/>
2) BT epoxy		UL approved <input type="checkbox"/>
3) Kevlar		UL approved <input type="checkbox"/>
4) Teflon	100	UL approved X Rogers 4350
5) Polyimide		UL approved <input type="checkbox"/>
6) Cyanate ester		UL approved <input type="checkbox"/>
7) Other		UL approved <input type="checkbox"/>
C) Specification to which laminate is purchased (check all that apply) XMIL-P-13949 <input type="checkbox"/> IPC-4204 XIPC-4101 XUL Approved <input type="checkbox"/> IPC-4103 <input type="checkbox"/> Other <input type="checkbox"/> IPC-4202 <input type="checkbox"/> IPC-4203		
D) Laminate storage <input type="checkbox"/> Uncontrolled XHumidity controlled XTemperature controlled <input type="checkbox"/> Dry box X JIT inventory		
E) Panel size configurations in X, Y dimensions maximum X <u>20</u> Y <u>24</u> mm minimum X <u>8</u> Y <u>9</u> mm other X _____ Y _____mm		

4.2.2 PROCESS PRECISION SPECIFICS	YES	NO	VALUE	COMMENTS
A) Maximum printed board thickness built in volume	X		.125	
1) Single sided	X		.125	
2) Double sided	X		.125	
3) Multilayer	X		.125	
4) Rigid flex		X		
B) Printed board electrical performance capability				
1) Impedance control	X	<input type="checkbox"/>	+/- 5%	
2) Capacitance control	<input type="checkbox"/>	X		
3) Microstrip boards	X			
C) Tooling system description				
1) Same holes in panels used for all processes	X	<input type="checkbox"/>		Dedicated holes for primary image and LPI Image
2) Optical registration	X			Process: Film and post etch punch
3) Other	X	<input type="checkbox"/>		Glass frame registration

4.2.3 OTHER PROCESS ORIENTATION SPECIFICS	YES	NO	SYSTEM	COMMENTS
A) Solder mask over bare copper	X	<input type="checkbox"/>	LPI	
B) Plating/coating information				
1) Tin/lead reflow	<input type="checkbox"/>	X		
2) Hot air leveling	X	<input type="checkbox"/>		
3) Azole organic	X			
4) Conductive	X	<input type="checkbox"/>	Carbon Ink & Immersion white tin ENIG, Immersion Silver, Lead free HASL	
C) Hole formation				
1) Hole cleaning	X	<input type="checkbox"/>	Chemical	
2) Hole cleanliness verified	X	<input type="checkbox"/>		

4.3 PRODUCT DESCRIPTION

*CONSISTENCY IMPLIES YIELDS IN EXCESS OF 80%

4.3.1. THROUGH HOLE INSERTION	EST %	SIZE (MM) - +/- TOL	COMMENTS
A) Smallest conductor width and tolerance produced with consistency			
1) Outer layers (print and etch)		Size <u>.004 in</u> Tol \pm <u>20%</u>	
2) Inner layers (print and etch)		Size <u>.004 in</u> Tol \pm <u>20%</u>	
3) Outer layers (plated)		Size <u>.004 in</u> Tol \pm <u>20%</u>	
4) Inner layers (plated)		Size <u>.004 in</u> Tol \pm <u>20 %</u>	
5) Outer layers (additive plating)		Size _____ mm Tol \pm _____ .mm	
6) Inner layers (additive plating)		Size _____ mm Tol \pm _____ .mm	
B) Smallest plated-through hole (PTH) and tolerance consistently produced in 1.5mm thickness material or multilayer board			
1) Minimum PTH diameter		Size <u>.006 in</u> Tol \pm <u>.003 in</u>	.008 drilled
2) Largest panel where this hole can be controlled (across diagonal)		Size _____ mm Tol \pm _____ .mm	20 * 24 in
C) Largest hole size that can be drilled and plated through in a 1.25mm diameter land while maintaining an annular ring of 0.125mm in large/small boards			
1) Largest board size (across diagonal)		Size _____ mm	20 * 24 in
2) Largest hole diameter		Size <u>.250 in</u>	
3) Smallest board size (across diagonal)		Size _____ mm	8 * 9 in
4) Largest hole diameter		Size <u>.250 in</u>	
D) Surface mount land pattern pitch (check all that apply) X1.27mm [.050] X0.63mm [.025] X0.5mm [.020] X0.4mm [.016] <input type="checkbox"/> 0.3mm [.012] <input type="checkbox"/> 0.25mm [.010] <input type="checkbox"/> Other _____ .			

E) Solder mask dam between lands (check all that apply) X1.27mm [.050] X0.63mm [.025] X0.5mm [.020] X0.4mm [.016] X0.3mm [.012] X0.25mm [.010] XOther to .003 in			
F) Flatness tolerance (bow & twist) after reflow or solder coating X1.5% <input type="checkbox"/> 1.0% <input type="checkbox"/> 0.5% <input type="checkbox"/> Other ____			

4.3.2 PRODUCT QUALITATIVE AND QUANTITATIVE INFORMATION	YES	NO	QUANTITY OF PANELS	NUMBER of DIMENSION	COMMENTS
A) Multilayer layer count					
1) Maximum layers fabricated in volume (Maximum Lot)	X		12		
2) Maximum layers fabricated in prototype (Minimum Lot)	X		12		
B) Buried vias produced consistently in volume	<input type="checkbox"/>				
1) Size					
2) Number of layers					
B) Blind vias produced consistently in volume	<input type="checkbox"/>	<input type="checkbox"/>			
1) Size					
2) Number of layers					
1) Controlled depth drilling	X	<input type="checkbox"/>			
2) Total number of layers	2				

4.4. TESTING CAPABILITY

4.4.1 TEST AND TEST EQUIPMENT CAPABILITY	YES	NO	COMMENTS
A) SMT centerline pitch that can be electrically tested X 0.63mm [.025] X 0.5mm [.020]X X0.4mm [.016] <input type="checkbox"/> 0.3mm [.012] <input type="checkbox"/> 0.25mm [.010] <input type="checkbox"/> Other			
B) Double sided simultaneous electrical testing	X	<input type="checkbox"/>	
1) Equipment type	X	<input type="checkbox"/>	Evertt Charles-Clamshell Mania-Flying Probe
2) X-ray fluorescence inspection equipment	X	<input type="checkbox"/>	CMI
3) TDR equipment	<input type="checkbox"/>	X	
4) Hi-pot test equipment	<input type="checkbox"/>	X	
5) Four-wire kelvin tester	<input type="checkbox"/>	X	

6) Capacitance meter	<input type="checkbox"/>	X	
7) Cleanliness testing	X	<input type="checkbox"/>	Ionic graph

4.4.2 AUTOMATED OPTICAL INSPECTION USAGE	EST %	COMMENTS
A) Before etching	Yes	
B) After etching	Yes	All .006 linear/space product or below
C) Internal layers	100	
D) Final inspection		
E) Other	Yes	Photo tool or 1st piece as required
F) Conductor/clearance normally inspected by AOI equipment		
1) <input type="checkbox"/> 0.05mm [.002]	No	
2) <input type="checkbox"/> 0.05-.10mm [.002-.004]	No	
3) <input type="checkbox"/> >.10mm [.004]	Yes	100%
4) <input type="checkbox"/> Planes	Yes	100%
G) CAD download to AOI	Yes	100%

SECTION 5

QUALITY PROFILE

DATE COMPLETED
8/31/2009

GENERAL INFORMATION

COMPANY NAME

Triangle Circuits of Pgh Inc

CONTACT

Frank Padol

TELEPHONE NUMBER

(412)828-5322 x635

FAX NUMBER

(412)828-5803

This section of the Manufacturer's Qualification Profile is intended to describe the Total Quality Management (TQM) activity in place of being implemented at the manufacturing facility identified in the site description of this MQP.

To ease in the task of identifying the TQM program being planned or underway at the manufacturing site, the activities have been divided into twenty sections which when completed, provide the total picture of the posture toward managing quality issues. Each section contains a number of questions with regard to the topic under review.

It is not the intent to have the questions be all encompassing, nor is every question applicable to all manufacturers. However, identification of the status, related to each questions, when considered as a whole will convey an impression of the progress that the company has achieved in adopting the principles of total quality management.

The twenty sections, in order of the occurrence are:

- 5.1 General Quality Programs
- 5.2 New Products/Technical Services
- 5.3 Customer Satisfaction
- 5.4 Computer Integrated Manufacturing
- 5.5 Process Documentation
- 5.6 Quality Records
- 5.7 Skill, Training & Certification
- 5.8 Subcontractor Control
- 5.9 Calibration Control
- 5.10 Internal Audits
- 5.11 Statistical Process Control
- 5.12 Problem Solving
- 5.13 In-Process Control
- 5.14 Receiving Inspection
- 5.15 Material Handling
- 5.16 Non-Conforming Material Control
- 5.17 Inspection and Test Plan
- 5.18 Product Inspection/Final Audit
- 5.19 Tooling Inspection, Handling, & Storage
- 5.20 Corrective Action

Each section provides a status report related to each question. The question may not be applicable, no activity has started as yet, or the company may have developed an approach to the issues raised by the questions. An (X) is indicated in the appropriate column. If deployment/implementation has started, the status is reported as percent deployment; this is indicated in column 4. The percentage number closely approximates the status of deployment. If deployment exists, the percentage results that have been achieved is indicated in column 5. Results are based on expected goals. Not providing percent information in either the deployment or results column implies a lack of activity in the particular area.

The quality descriptions requested are completed on the following pages by checking (X) the appropriate column to reflect the status of the manufacturing facility TQM program. Additional information may be provided as comments shown below, or on individual sections, or additional sheets as necessary.

COMMENTS

5.1 GENERAL QUALITY PROGRAMS		STATUS				
		Not Applicable	Not Started	Approach Developed	Percent Deployed	Percent Results
DESCRIPTION OF PROGRAM						
1.	Are quality objectives and responsibilities clearly stated, widely distributed and understood through the company?			X	100	100
2.	Is there a quality function or well defined organization which provides customer advocate guidance to the total organization and is this position fully supported by management?			X	100	100
3.	Does a quality measurement system exist with clearly defined metrics and is it utilized as a management tool?			X	100	100
4.	Are work instructions approved and controlled; and are they under revision control?			X	100	100
5.	Are the quality procedures and policies current and available at the point of application; and are they under revision control?			X	100	100
6.	Are benchmark and customer satisfaction studies done to determine best in class for all products, services, and administrative functions; and are quality goals set?			X	100	100
7.	Are Statistical Process Control (SPC) principles understood by all levels of management?			X	100	100
8.	Are there programs with sufficient resources assigned to support corrective actions and prevention?			X	100	100
9.	Does management solicit and accept feedback from the work force?			X	100	100
10.	Is there management support of ongoing training (including quality training), and is it documented by an organizational training plan?			X	100	100
11.	Are there regular management reviews of elements of the quality improvement process, including feedback for corrective action, and are the results acted upon?			X	100	100
12.	Are the quality and reliability goals aggressive relative to customer expectations and targeted at continuous improvement?			X	100	100
13.	Are the people who are responsible for administering the quality assurance function technically informed?			X	100	100
14.	Does Management have a "defect prevention" attitude to achieve continuous improvement?			X	80	80

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5.2 NEW PRODUCTS/TECHNICAL SERVICES		STATUS				
		Not Applicable	Not Started	Approach Developed	Percent Deployed	Percent Results
DESCRIPTION OF PROGRAM						
1.	Do new product/technology/service development policies and procedures exist, and do they result in clearly defined project plans with appropriate measureables and approvals?			X	90	90
2.	Is quantitative benchmarking used to evaluate all new products/technologies/services in comparison to best-in-class offerings?			X	80	80
3.	Does a roadmap exist to ensure continued development of leading edge, best-in-class products/technology/services?			X	90	90
4.	Is the capability of each operation which controls critical-to-function characteristics for new products, fully certified?			X	100	100
5.	Are statistical tools used in the development of robust (high yield) new processes, products, and services?			X	80	80
6.	When new product/technology/service requires a new process, is it developed jointly and concurrently with the customer and/or suppliers?			X	100	100
7.	Are design reviews conducted on a scheduled basis which properly address the process capability indices of critical-to-function and product/service characteristics?			X	100	100
8.	Is the new product/technology/service, as produced by the process, verified to meet all customer satisfaction requirements?			X	100	100

COMMENTS

5.3 CUSTOMER SATISFACTION		STATUS				
		Not Applicable	Not Started	Approach Developed	Percent Deployed	Percent Results
DESCRIPTION OF PROGRAM						
1.	Is there a measurement system in place to assess the customer's perception of complete performance?			X	100	100
2.	Is an independent (unbiased) customer survey routinely conducted?			X	100	100
3.	Is there an internal measurement system within the organization which correlates to the level of customer satisfaction?			X	90	90
4.	Are there specific goals for achieving Total Customer Satisfaction, both internal and external?			X	100	95
5.	To what extent are customer satisfaction goals disseminated and understood by everyone in the organization?			X	90	90
6.	Does management regularly review and assess all operating systems to determine if barriers to customer satisfaction exist and are appropriate action plans then implemented?			X	100	100
7.	Is there a method in place to obtain future customer requirements?			X	100	100
8.	Are all findings of customer dissatisfaction reported back to the proper organization for analysis and corrective action?			X	100	100
9.	Are customer satisfaction requirements formally defined and documented, and are they based on customer input?			X	100	100
10.	Do all support organizations understand their role in achieving total customer satisfaction?			X	90	90

5.4 COMPUTER INTEGRATED MANUFACTURING		STATUS				
		Not Applicable	Not Started	Approach Developed	Percent Deployed	Percent Results
DESCRIPTION OF PROGRAM						
1.	Are systems integrated to allow electronic transfer of information between multiple systems to eliminate redundant data entry?			X	100	100
2.	Can customers electronically transfer CAD/CAM directly into manufacturing?			X	100	100
3.	Can customers electronically transfer order information directly into the business system?	X				
4.	Is data electronically shared between shop floor control and process control systems (i.e., CNC, SPC, Electrical Test, AOI, etc.)?			X	100	100
5.	Are planning systems (MRP, forecasting, capacity planning, financial planning, etc.) electronically integrated with operation systems (order processing, purchasing, inventory management, shop floor control, financial/cost control, etc.)?			X	100	100
6.	Is information available from system processes in real time (vs. batch processing)?			X	100	100
7.	Are processes and procedures documented and available on-line?	X				
8.	Do all functional departments have system access to key financial, manufacturing, sales, and operational data, as it relates to their functional objectives?			X	100	100
9.	Are computer simulation and design tools used to the maximum extent practicable in the design of new products/technologies/services			X	100	100

COMMENTS						

5.5 PROCESS DOCUMENTATION		STATUS				
		Not Applicable	Not Started	Approach Developed	Percent Deployed	Percent Results
DESCRIPTION OF PROGRAM						
1.	Are manufacturing product, process, and configuration documents under issue control?			X	100	100
2.	Are "preliminary" and "special product" specifications controlled?			X	100	100
3.	Does the system ensure that the most current customer specifications are available to the manufacturing personnel?			X	100	100
4.	Does the system ensure that the most current material specifications are available to the procurement function?			X	100	100
5.	Are incoming orders reviewed for revisions and issue changes?			X	100	100
6.	Is conformance to customer specifications assured before an order is accepted?			X	100	100
7.	Is customer feedback provided when designs do not meet manufacturability requirements?			X	100	100
8.	Are critical characteristics classified, relative to impact on product performance?			X	100	100
9.	Are customers informed of changes made to products controlled by customer drawings or specifications?			X	100	100
10.	Is there an effective internal deviation control procedure and, are customer requested deviations documented and followed?			X	100	100
11.	Do new product development procedures exist, and are they followed in the design development process?			X	100	100

5.6 QUALITY RECORDS		STATUS				
		Not Applicable	Not Started	Approach Developed	Percent Deployed	Percent Results
DESCRIPTION OF PROGRAM						
1.	Are records of inspection and process control maintained and available for review?			X	100	100
2.	Are records of equipment and equipment maintenance kept?			X	100	100
3.	Is the record and sample retention program defined?			X	100	100
4.	Are quality data used as a basis for corrective action?			X	100	100
5.	Are quality data used in reporting performance and trends to management?			X	100	100
6.	Are quality data used in supporting certifications of quality furnished to customers?			X	100	100
7.	Is field information used for corrective action?			X	100	100
8.	Does a cost of quality measurement system exist?			X	90	90
9.	Are customer reported quality problems responded to, and resolved in the time period requested?			X	100	100
10.	Is quality information on production material rejects provided to sub-suppliers with required corrective action?			X	100	100
11.	Are computers used to collect and analyze quality data?			X	100	100

COMMENTS

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5.7 SKILLS, TRAINING, & CERTIFICATION		STATUS				
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DESCRIPTION OF PROGRAM		Not Applicable	Not Started	Approach Developed	Percent Deployed	Percent Results
1.	Does management ensure that all personnel are trained in their role for achieving Total Customer Satisfaction?			X	100	100
2.	Do all personnel understand how their performance impacts internal and external customer satisfaction?			X	100	100
3.	Do all personnel who contact external customers reflect quality improvement programs?			X	100	100
4.	Do personnel participate in professional societies and growth programs?			X	100	100
5.	Are all personnel trained in sufficient detail to support key initiatives?			X	100	100
6.	Are the results of training evaluated and indicated program changes made?			X	100	100
7.	Does a policy exist which encourages the cross training and rotation of personnel, and is this policy used as the basis of job progression?			X	100	100
8.	Are performance standards participatively developed, and regularly applied for all personnel?			X	100	100
9.	Are Total Customer Satisfaction programs and resulting successes publicized to all personnel?			X	100	100
10.	Do goal setting and reward/incentive programs support the quality improvement process?			X	100	100

5.8 SUBCONTRACTOR CONTROL		STATUS				
DESCRIPTION OF PROGRAM		Not Applicable	Not Started	Approach Developed	Percent Deployed	Percent Results
1.	Are requirements defined, communicated, and updated to ensure that the supplier understands expectations?			X	100	100
2.	Does a system exist which measures the performance of the supplier and communicates such information to the supplier? (i.e., supplier rating system)			X	100	100
3.	Have the organization's processes been characterized to identify the critical requirements for the suppliers products?			X	100	100
4.	Have the capabilities of the supplier's processes been assessed and considered in the establishment of the requirements?			X	100	100
5.	Have partnerships been established with suppliers, and is assistance provided to ensure that each supplier has the capability to consistently supply conforming products?			X	100	100
6.	Have quality and cycle time metrics and improvement goals been established participatively with the supplier?			X	100	100
7.	Has a system been established with the supplier for identification and verification of corrective action?			X	100	100
8.	Have the requirements for supplier materials been properly characterized and specified to ensure conformance of the product/service to the customer satisfaction requirements?			X	100	100
9.	Is there a supplier certification program or equivalent procured material/service continuous quality improvement program?			X	100	75
10.	Can all personnel who contract suppliers properly reflect appropriate quality improvement programs and status to them?			X	100	100

COMMENTS

5.9 CALIBRATION CONTROL		STATUS				
DESCRIPTION OF PROGRAM		Not Applicable	Not Started	Approach Developed	Percent Deployed	Percent Results

1.	Are calibration and preventative maintenance programs in place and documented?			X	100	100
2.	Are calibration and maintenance personnel trained?			X	100	100
3.	Is traceability to NIST maintained?			X	100	100
4.	Is quality measurement and control equipment current, effective, and sufficiently integrated with production equipment?			X	100	100
5.	Is the history of quality measurement and control equipment documented?			X	100	100
6.	Has repeatability of measuring devices and inspection or testing processes been established and monitored; are gauge capability studies conducted and GR&R ratios acceptable(<10%)?			X	100	100
7.	Are calibration and preventative maintenance cycles on schedule?			X	100	100
8.	Is the use of non-calibrated equipment for design and production purposes prohibited?			X	100	100
9.	Are tools and fixtures used as criteria or acceptability of product/work fully qualified and identified?			X	100	100
10.	Are calibration intervals defined in accordance with industry standards or manufacturer's recommendations and the calibration history of the equipment?			X	100	100

5.10 INTERNAL AUDITS		STATUS				
		Not Applicable	Not Started	Approach Developed	Percent Deployed	Percent Results
DESCRIPTION OF PROGRAM		Not Applicable	Not Started	Approach Developed	Percent Deployed	Percent Results
1.	Are regular reviews of the product/process conducted and are goals/plans established to continually improve?			X	100	100
2.	Are the processes/products properly documented and controlled? Do they include appropriate customer requirements and are they executed in conformance to the documentation?			X	100	100
3.	Are the required quality checks built into the operations within the manufacturing, field installation, and service process, and is the resulting data maintained and promptly acted upon?			X	100	100
4.	Are all pertinent methods of statistical quality control properly, effectively and efficiently used?			X	100	100
5.	Does a process change control system exist, and are customers informed of changes made to products and processes with customer approval prior to the change, when required?			X	100	100
6.	Are the operators within the process provided with written work instructions and are they trained?			X	100	100
7.	Is the receipt, handling, storage, packaging and release of all material, including customer provided items, at all stages, specified and controlled to prevent damage or deterioration, and to address obsolete material?			X	100	100
8.	Is there a first in/first out (FIFO) system in place, and is it followed?			X	100	100

COMMENTS

5.11 STATISTICAL PROCESS CONTROL		STATUS				
		Not Applicable	Not Started	Approach Developed	Percent Deployed	Percent Results
DESCRIPTION OF PROGRAM						
1.	Have the personnel who will be responsible for guiding the implementation of SPC been designated?			X	100	100
2.	Are statistical techniques used to reduce variation in the engineering process before the start of production?			X	100	100
3.	Is the quality system dependent upon process rather than product controls?			X	100	100
4.	Is the capability of critical processes and machines measured and monitored with CPK's >1.5, and targeted with CP of 2.0?			X	100	100
5.	Are incapable processes or machines targeted for improvement or replacement?			X	100	100
6.	Is SPC implemented for all critical processes?			X	100	100
7.	Are procedures that control the reaction to out-of-control situations adequate and effective?			X	100	100
8.	Are operators trained in the use of appropriate statistical techniques, and are they properly applying them?			X	75	75
9.	Are advanced problem solving techniques used by engineers to solve problems? (Design of Experiments, planned experimentation, advanced diagnostic tools, etc.)			X	50	50
10.	Are control charts and other process controls properly implemented?			X	100	100
11.	Is statistical process control being practiced in work centers and are yields being recorded and plotted on a scheduled basis, with respect to upper and lower control limits?			X	90	90

5.12 PROBLEM SOLVING		STATUS				
		Not Applicable	Not Started	Approach Developed	Percent Deployed	Percent Results
DESCRIPTION OF PROGRAM						
1.	Are employees trained in problem solving techniques, in comparison to the needs of the organization?			X	50	50
2.	Does the organization utilize participative problem solving techniques to identify, measure and resolve internal and external problems?			X	100	100
3.	Are problem solving efforts timely and effective?			X	100	100
4.	Are applied resources sufficient to remove problem solving constraints?			X	100	100
5.	Are statistical techniques used for problem solving?			X	100	100
6.	Are quality data used to identify barriers, and to determine the priority of problems?			X	90	90
7.	Is there a policy/procedure that includes the use of problem solving techniques to systematically drive reduction in variability?			X	100	100

COMMENTS						

5.13 IN-PROCESS CONTROL		STATUS				
		Not Applicable	Not Started	Approach Developed	Percent Deployed	Percent Results
DESCRIPTION OF PROGRAM						
1.	Are process capabilities established and maintained on all major processes? (critical parameters)			X	100	100
2.	Are in-process inspections, test operations, and processes properly specified and performed?			X	100	100
3.	Are in-process inspection facilities and equipment adequate?			X	100	100
4.	Are the results of in-process inspections used in the promotion of effective preventative action and corrective action?			X	100	100
5.	Is preventative maintenance performed on the equipment and facilities?			X	100	100
6.	Are housekeeping procedures adequate and how well are they followed?			X	100	100
7.	Are process management plans established, and are critical parameters followed?			X	100	100
8.	Are work areas uncluttered and free of excess work-in-process, supplies, debris, etc? Is the environment conducive to producing quality work? Is proprietary information adequately protected?			X	100	100
9.	Are certifications and in-process inspection results used in making final acceptance decisions?			X	100	100
10.	Are methods and procedures for the control of metallurgical, chemical, and other special processes established and followed?			X	100	100

5.14 RECEIVING INSPECTION		STATUS				
		Not Applicable	Not Started	Approach Developed	Percent Deployed	Percent Results
DESCRIPTION OF PROGRAM						
1.	Are receiving inspection facilities and equipment adequately and properly maintained?			X	100	100
2.	Are receiving inspection procedures documented and followed?			X	100	100
3.	Are receiving inspection results used for corrective and preventive action?			X	100	100
4.	Are the procedures for storage and timely disposition of discrepant material in place and followed?			X	100	100

COMMENTS

5.15 MATERIAL HANDLING		STATUS				
		Not Applicable	Not Started	Approach Developed	Percent Deployed	Percent Results
DESCRIPTION OF PROGRAM						
1.	Are procured material releases from receiving inspection clearly identified, as to acceptance status?			X	100	100
2.	Are procedures to facilitate limited life materials, such as prepreg, in place, properly controlled, and monitored?			X	100	100
3.	Are procured items identified with some means of traceability (serial number, lot number, date code, etc.)?			X	100	100
4.	Are procedures and facilities adequate for storage, release and control of materials?			X	100	100
5.	Are in-store and in-process materials properly identified and controlled?			X	100	100
6.	Is in-process material protected from corrosion, deterioration, and damage?			X	100	100

5.16 NON-CONFORMING MATERIAL CONTROL		STATUS				
		Not Applicable	Not Started	Approach Developed	Percent Deployed	Percent Results
DESCRIPTION OF PROGRAM						
1.	Is non-conforming material identified, segregated from regular production material, and properly dispositioned?			X	100	100
2.	Are non-conforming materials properly identified and controlled to prevent inadvertent use?			X	100	100
3.	Is the review and disposition of non-conforming materials defined, and are provisions made for inclusion of the customer in disposition decision?			X	100	100
4.	Are procedures for controlling non-conforming materials, and for ensuing corrective action, in place and followed?			X	100	100
5.	Do procedures provide for material review by a committee consisting of Quality and Engineering (as a minimum), to determine the disposition of non-conforming materials? (deviating from drawings or specification)			X	100	100
6.	Do supplier's procedures and controls for corrective action prevent recurrence of non-conformances?			X	100	100
7.	Is there a system for coordinating necessary corrective action with purchasing personnel?			X	100	100
8.	Does the corrective action extend to all applicable causes of non-conformance (e.g., design, workmanship, procedures, equipment, etc.)?			X	100	100

COMMENTS

5.17 INSPECTION AND TEST PLAN		STATUS				
		Not Applicable	Not Started	Approach Developed	Percent Deployed	Percent Results
DESCRIPTION OF PROGRAM						
1.	Are statistical techniques used in determining the acceptability of finished goods to customer requirements?			X	100	100
2.	Are periodic tests conducted to audit reliability and environmental performance of the final product?			X	100	100
3.	Is CPK tracking performed for critical characteristics, with plans to achieve CPK = 1.5 with a target of CP of 2.0?			X	70	70
4.	Is root cause failure analysis performed for internal and external failures, and is appropriate corrective action implemented?			X	100	100
5.	Are test and inspection personnel trained in the procedures of their operations, and are those procedures being followed?			X	100	100
6.	Is the new product/technology/service, as produced by the processes, verified to meet all customer satisfaction requirements?			X	100	100

5.18 PRODUCT INSPECTION/FINAL AUDIT		STATUS				
		Not Applicable	Not Started	Approach Developed	Percent Deployed	Percent Results
DESCRIPTION OF PROGRAM						
1.	Are final product acceptance procedures documented and followed?			X	100	100
2.	Are all specific customer product audits conducted, as required?			X	100	100
3.	Are inspectors trained for the tasks performed?			X	100	100
4.	Are flow charts or milestones developed with checkpoints readily available?			X	100	100
5.	Is a system in place which denotes inspection performed; e.g., use of initials, stamps, labels, bar codes, etc., affixed to production documentation?			X	100	100
6.	Is a quality system established and maintained for control of product/production documentation?			X	100	100
7.	Is "accept/reject" criteria defined and available for use?			X	100	100
8.	Is a final audit performed to ensure that all required verifications and tests, from receipt of materials through point of product completion, have been accomplished?			X	100	100
9.	Are packing and order checking procedures documented and followed?			X	100	100

COMMENTS						

5.19 TOOLING INSPECTION, HANDLING, &		STATUS				
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STORAGE						
DESCRIPTION OF PROGRAM		Not Applicable	Not Started	Approach Developed	Percent Deployed	Percent Results
1.	Are temperature, humidity, laminar flow controls in place to prevent contamination, and to assure dimensional stability?			X	100	100
2.	Do operators use hairnets, gloves & lab coats in all photolab and photoexposure areas?			X	95	95
3.	Are work instructions and related forms in place to control all applicable tooling requirements, as stated in the customer's purchase order?			X	100	100
4.	Are customer provided artworks controlled with regard to handling, storage, revision control and relationship to converted production phototools (working films)?			X	100	100
5.	Are production phototools (working films) controlled with regard to handling, storage, use life, and relationship to customer purchase order?			X	100	100
6.	Are customer provided artworks and production phototools (working films) inspected, including dimensional checks?			X	100	100
7.	Are all tools, fixtures, and other devices, used for tooling inspection and control, maintained under the calibration control procedure?			X	100	100
8.	Are records showing initial acceptance, periodic checks, and any needs for rework and/or modification available?			X	100	100

5.20 CORRECTIVE ACTION		STATUS				
DESCRIPTION OF PROGRAM		Not Applicable	Not Started	Approach Developed	Percent Deployed	Percent Results
1.	Are final acceptance inspection results used for corrective and preventative action?			X	100	100
2.	Is root-cause analysis performed for non-conformances? This includes, but is not limited to, non-conformances (problems) caused by suppliers, found/caused "in-house" during processing, or those reported by the customer.			X	100	100
3.	Is positive action taken to prevent recurrence of problems, and are there documented reports/records of each occasion?			X	100	100
4.	Do procedures and systems provide for ensuring that replies are made to customer requests for correction action within the time limit specified?			X	100	100
5.	Is corrective action controlled and documented for all applicable work centers?			X	100	100
6.	When corrections are made, is their effectiveness subsequently reviewed and monitored?			X	100	100

COMMENTS	

SECTION 6 (CHECK ONE IN EACH LINE THAT APPLIES)

MANUFACTURING HISTORY (See Section 2 Site Capability)

DATE COMPLETED
Available upon
request

Please complete as many history profiles so that the total descriptions of products you manufacture account for production orders that reflect 70% of your business. History profiles are for board or board family (board types may be grounded together if they are similar).

BOARD TYPE	DATE OF ORDER	MATERIAL	HISTORY #
VIA TYPE	PRODUCTION QUANTITY	TOTAL YEARLY PRODUCTION %	

Dimensions in millimeters (inches in brackets)

BOARD			HOLES		
BOARD SIZE DIAGONAL	TOTAL BOARD THICKNESS	NUMBER CONDUCTIVE LAYERS	DIA DRILLED HOLES	TOTAL PTH TOL (MAX-MIN)	LOCATION TOL DTP
<input type="checkbox"/> <250 [<10.00]	<input type="checkbox"/> <1,0 [$<.040$]	<input type="checkbox"/> 1-4 [1-4]	<input type="checkbox"/> >0,5 [$>.020$]	<input type="checkbox"/> >0,250 [$>.010$]	<input type="checkbox"/> >0,50 [$>.020$]
<input type="checkbox"/> 250 [10.00]	<input type="checkbox"/> 1,0 [.040]	<input type="checkbox"/> 5-6 [5-6]	<input type="checkbox"/> 0,5 [.020]	<input type="checkbox"/> 0,250 [.010]	<input type="checkbox"/> 0,50 [.020]
<input type="checkbox"/> 350 [14.00]	<input type="checkbox"/> 1,6 [.060]	<input type="checkbox"/> 7-8 [7-8]	<input type="checkbox"/> 0,4 [.016]	<input type="checkbox"/> 0,200 [.008]	<input type="checkbox"/> 0,40 [.016]
<input type="checkbox"/> 450 [17.50]	<input type="checkbox"/> 2,0 [.080]	<input type="checkbox"/> 9-12 [9-12]	<input type="checkbox"/> 0,35 [.014]	<input type="checkbox"/> 0,150 [.006]	<input type="checkbox"/> 0,30 [.012]
<input type="checkbox"/> 550 [21.50]	<input type="checkbox"/> 2,5 [.100]	<input type="checkbox"/> 13-16 [13-16]	<input type="checkbox"/> 0,30 [.012]	<input type="checkbox"/> 0,125 [.005]	<input type="checkbox"/> 0,25 [.010]
<input type="checkbox"/> 650 [25.50]	<input type="checkbox"/> 3,5 [.135]	<input type="checkbox"/> 17-20 [17-20]	<input type="checkbox"/> 0,25 [.010]	<input type="checkbox"/> 0,100 [.004]	<input type="checkbox"/> 0,20 [.008]
<input type="checkbox"/> 750 [29.50]	<input type="checkbox"/> 5,0 [.200]	<input type="checkbox"/> 21-24 [21-24]	<input type="checkbox"/> 0,20 [.008]	<input type="checkbox"/> 0,075 [.003]	<input type="checkbox"/> 0,15 [.006]
<input type="checkbox"/> 850 [33.50]	<input type="checkbox"/> 6,5 [.250]	<input type="checkbox"/> 25-28 [25-28]	<input type="checkbox"/> 0,15 [.006]	<input type="checkbox"/> 0,050 [.002]	<input type="checkbox"/> 0,10 [.004]
<input type="checkbox"/> >850 [>33.50]	<input type="checkbox"/> >6,5 [$>.250$]	<input type="checkbox"/> >28 [>28]	<input type="checkbox"/> <0,15 [.006]	<input type="checkbox"/> <0,050 [$<.002$]	<input type="checkbox"/> <0,10 [$<.004$]
<input type="checkbox"/> Other:	<input type="checkbox"/> Other:	<input type="checkbox"/> Other:	<input type="checkbox"/> Other:	<input type="checkbox"/> Other:	<input type="checkbox"/> Other:

CONDUCTORS

INTERNAL ELEC CLEARANCE (MIN)	INTERNAL COND WIDTH (MIN)	INTERNAL PROCESS ALLOWANCE	EXTERNAL ELEC CLEARANCE (MIN)	EXTERNAL COND WIDTH (MIN)	EXTERNAL PROCESS ALLOWANCE	FEATURE LOCATION DTP
<input type="checkbox"/> >0,350 [$>.014$]	<input type="checkbox"/> >0,250 [$>.010$]	<input type="checkbox"/> >0,100 [$>.004$]	<input type="checkbox"/> >0,350 [$>.014$]	<input type="checkbox"/> >0,250 [$>.010$]	<input type="checkbox"/> >0,100 [$>.004$]	<input type="checkbox"/> >0,50 [$>.020$]
<input type="checkbox"/> 0,350 [.014]	<input type="checkbox"/> 0,250 [.010]	<input type="checkbox"/> 0,100 [.004]	<input type="checkbox"/> 0,350 [.014]	<input type="checkbox"/> 0,250 [.010]	<input type="checkbox"/> 0,100 [.004]	<input type="checkbox"/> 0,50 [.020]
<input type="checkbox"/> 0,250 [.010]	<input type="checkbox"/> 0,200 [.008]	<input type="checkbox"/> 0,075 [.003]	<input type="checkbox"/> 0,250 [.010]	<input type="checkbox"/> 0,200 [.008]	<input type="checkbox"/> 0,075 [.003]	<input type="checkbox"/> 0,40 [.016]
<input type="checkbox"/> 0,200 [.008]	<input type="checkbox"/> 0,150 [.006]	<input type="checkbox"/> 0,050 [.002]	<input type="checkbox"/> 0,200 [.008]	<input type="checkbox"/> 0,150 [.006]	<input type="checkbox"/> 0,050 [.002]	<input type="checkbox"/> 0,30 [.012]
<input type="checkbox"/> 0,150 [.005]	<input type="checkbox"/> 0,125 [.005]	<input type="checkbox"/> 0,040 [.0015]	<input type="checkbox"/> 0,150 [.006]	<input type="checkbox"/> 0,125 [.005]	<input type="checkbox"/> 0,040 [.0015]	<input type="checkbox"/> 0,25 [.010]
<input type="checkbox"/> 0,125 [.005]	<input type="checkbox"/> 0,100 [.004]	<input type="checkbox"/> 0,030 [.0012]	<input type="checkbox"/> 0,125 [.005]	<input type="checkbox"/> 0,100 [.004]	<input type="checkbox"/> 0,030 [.0012]	<input type="checkbox"/> 0,20 [.008]
<input type="checkbox"/> 0,100 [.004]	<input type="checkbox"/> 0,075 [.003]	<input type="checkbox"/> 0,025 [.001]	<input type="checkbox"/> 0,100 [.004]	<input type="checkbox"/> 0,075 [.003]	<input type="checkbox"/> 0,025 [.001]	<input type="checkbox"/> 0,15 [.006]
<input type="checkbox"/> 0,075 [.003]	<input type="checkbox"/> 0,050 [.002]	<input type="checkbox"/> 0,020 [.0008]	<input type="checkbox"/> 0,075 [.003]	<input type="checkbox"/> 0,050 [.002]	<input type="checkbox"/> 0,020 [.0008]	<input type="checkbox"/> 0,10 [.004]
<input type="checkbox"/> <0,075 [$<.003$]	<input type="checkbox"/> <0,050 [$<.002$]	<input type="checkbox"/> <0,020 [$<.0008$]	<input type="checkbox"/> <0,075 [$<.003$]	<input type="checkbox"/> <0,050 [$<.002$]	<input type="checkbox"/> <0,020 [$<.008$]	<input type="checkbox"/> <0,10 [$<.004$]
<input type="checkbox"/> Other:	<input type="checkbox"/> Other:	<input type="checkbox"/> Other:	<input type="checkbox"/> Other:	<input type="checkbox"/> Other:	<input type="checkbox"/> Other:	<input type="checkbox"/> Other:

SECTION 7

DATE COMPLETED
Available upon request

IDENTIFICATION OF PREVIOUS AUDITS (Optional)

Please complete as many forms as you feel reflect the intensity of your customer visits.

COMPANY AUDITORS	DATE OF AUDIT
AUDIT TEAM MEMBERS	AUDITOR REMARKS
	SPECIFICATIONS USED IN AUDIT
LENGHT OF AUDIT	
TEAM MEMBERS MAY BE CONTACTED AT	
COMPANY AUDITORS	DATE OF AUDIT
AUDIT TEAM MEMBERS	AUDITOR REMARKS
	SPECIFICATIONS USED IN AUDIT
LENGHT OF AUDIT	
TEAM MEMBERS MAY BE CONTACTED AT	
COMPANY AUDITORS	DATE OF AUDIT
AUDIT TEAM MEMBERS	AUDITOR REMARKS
	SPECIFICATIONS USED IN AUDIT
LENGHT OF AUDIT	
TEAM MEMBERS MAY BE CONTACT AT	

*REPEAT THIS FORM AS NECESSARY

SECTION 8

DATE COMPLETED Available upon request
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FINANCIAL REVIEW (OPTIONAL)

Please complete the following financial information that coincides with the company description and site information provided in section 1.

COMPANY FINANCIAL DESCRIPTION

LEGAL NAME		
TAXPAYER ID NUMBER	DUNS NUMBER	TRADING SYMBOL
ANNUAL SALES	PRIOR YEAR	YEAR-TO-DATE
FISCAL YEAR		
BANK	ACCOUNT NUMBER	
BANK ADDRESS	STATE	ZIP
PROVINCE	COUNTRY	
BANK TELEPHONE NUMBER	FAX NUMBER	
COMMENTS		

SITE FINANCIAL DESCRIPTION

SITE NAME		
TAXPAYER ID NUMBER	DUNS NUMBER	TRADING SYMBOL
ANNUAL SALES	PRIOR YEAR	YEAR-TO-DATE
FISCAL YEAR		
BANK	ACCOUNT NUMBER	
BANK ADDRESS	STATE	ZIP
PROVINCE	COUNTRY	
BANK TELEPHONE NUMBER	FAX NUMBER	
COMMENTS		

SECTION 9

MQP ELECTRONIC EDITING

This MS Word template comes with editable fields. IPC has made this electronic document available for ease of completing, updating, and filing the MQP, as well as to give the laminate manufacturer and customer a common interface. Using the template enables laminate manufacturers to maintain several customer specific files without the endless stream of paperwork.

Editable fields are highlighted in gray. To complete the fields in the template, use the TAB key to toggle from field to field, entering the information as instructed in the introductory text for each section.

The developers of this MQP strongly suggest the person at the laminate manufacturing facility responsible for creating and maintaining the MQP write protect the file to be sent.